

KB-1150/1151 (ANSI : XPC/JIS:PP7)

覆銅箔酚醛樹脂紙基層壓板

特點

- 成本低而使用範圍廣
- 彎曲度、扭曲度小且穩定
- 適合之沖孔溫度為常溫~70℃

Features

- Low cost but with wide range of application
- Warpage and twist are small and stable
- Suitable for punching at Ambient~70℃

General Properties 一般特性

Test Item 測試項目	Unit 單位	Condition 處理條件	Testing Method 測試方法	Specification 規格值	Typical Value 典型值
Solder Resistance(260℃) 耐浸焊性	Sec	A	JIS C 6481	≥10	15~30
Heat Resistance 耐熱性	—	130℃ 30min	JIS C 6481	No Change 無異常	No Change 無異常
Peer Strength(Copper Foil 35μm) 銅箔剝離強度(35μm銅箔)	Kgf/cm	A 260℃/5Sec	JIS C 6481	≥1.2	1.7~1.9 1.6~1.8
Flexural Strength 屈曲強度	Lengthwise 縱向	A	JIS C 6481	≥8	14~16 13~14
	Crosswise 橫向				
Volume Resistivity 體積阻抗係數	Ω-cm	C-96/20/65 C-96/20/65+C-96/40/90	JIS C 6481	1×10 ⁹ 1×10 ⁸	1×10 ¹¹ ~10 ¹² 1×10 ⁹ ~10 ¹⁰
Surface Resistance 表面抗阻	Adhesive Side 粘接劑面	C-96/20/65 C-96/20/65+C-96/40/90	JIS C 6481	1×10 ¹⁰ 1×10 ⁹	1×10 ¹¹ ~10 ¹² 1×10 ¹⁰ ~10 ¹¹
	Laminate Side 積層板面	C-96/20/65 C-96/20/65+C-96/40/90		— —	— —
Insulation Resistance 絕緣抗阻	Ω	C-96/20/65 C-96/20/65+D-2/100	JIS C 6481	1×10 ⁹ 1×10 ⁶	1×10 ¹⁰ ~10 ¹¹ 1×10 ⁷ ~10 ⁸
Chemical Resistance 耐化學性	—	3% NaOH 40℃ 3min 3% 氫氧化鈉 40℃ 3 分鐘	JIS C 6481	No change 無異常	No change 無異常
		Boild in trichloroethylene for 3 min 三氯乙烯中煮沸 3 分鐘		No change 無異常	No change 無異常
Water Absorption 吸水性	%	E-24/50+D-24/23	JIS C 6481	≤2	1.0~1.5
Flammability 阻燃性	Sec	A	UL94	94HB	94HB
Dielectric Constant (1 MHz) 介電常數 (1 MHz)	—	C-96/20/65	JIS C 6481	≤5.5	4.0~5.0
		C-96/20/65+D-24/23		≤6.0	4.5~5.5
Dissipation Factor 介質損耗因數	—	C-96/20/65	JIS C 6481	≤0.05	0.025~0.035
		C-96/20/65-D-24/23		≤0.1	0.035~0.045
CTI Value CTI 值	V	01% NH ₄ Cl	IEC 112	—	125
Punching Temperature 沖孔溫度	℃	A	WI-QA-002	50~70	Ambient~70

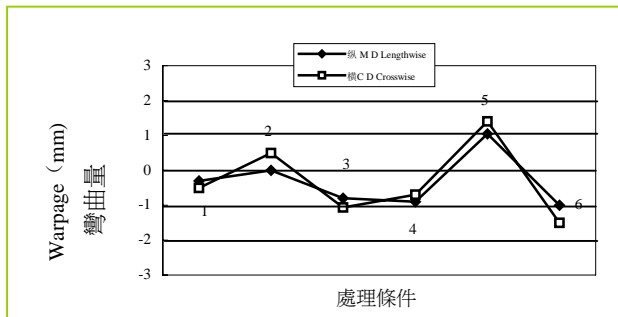
Remarks: Typical values for reference only 注: 典型值只作參考 Stand values according to JIS-C-6485 規格值參照 JIS-C-6485

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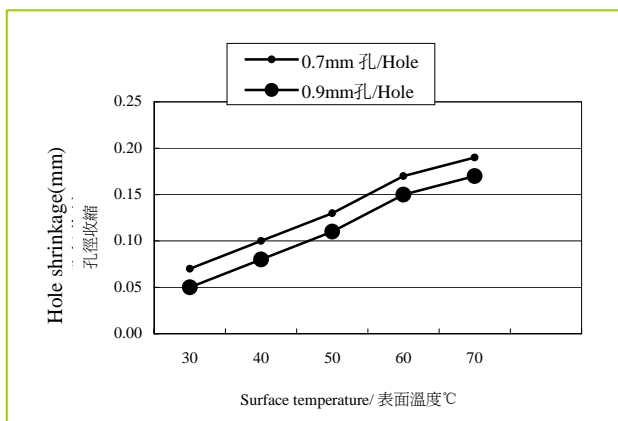
Speciality Chart 板材特性圖

Warpage of PCB during processing/印製電路板
加工時彎曲度(Thickness 1.6mm single side)

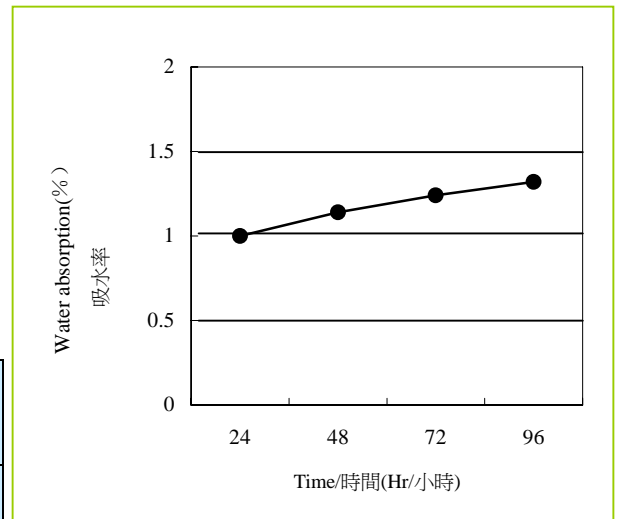


1. Feeding 投料	2. Heating at 130°C for 90 sec 130°C下加熱 90 秒	3. Etching. Rinsing, Drying 蝕刻, 清洗, 烘乾
4. Heating at 200°C for 30 sec 200°C下加熱 30 秒	5. Punching at 50°C 50°C下沖孔	6. Soldering at 260°C for 5 sec 260°C 焊錫 5 秒

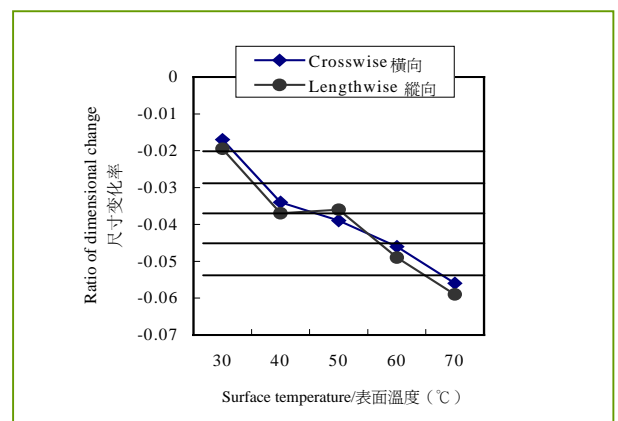
Punched hole shrinkage
沖孔後孔徑收縮



Water absorption 吸水率



Dimensional change of punched PCB
沖孔後之尺寸變化



Purchasing Information / 採購資訊

Type 類型	Thickness 厚度	Copper Cladding 銅箔厚度	Regular Size (mm) 常規尺寸	CTI Value CTI 值
KB-1150/1151 (HB 非阻燃紙板)	0.8mm ~ 1.6mm	18μm 35μm 70μm.	1020*1020mm (40" *40") 1020*1220mm (40" *48")	125V

Note: Other sheet size and thickness could be available upon request.

可根據客戶要求提供其他尺寸和厚度。